

Dual N-Channel Logic Level Enhancement Mode MOSFET

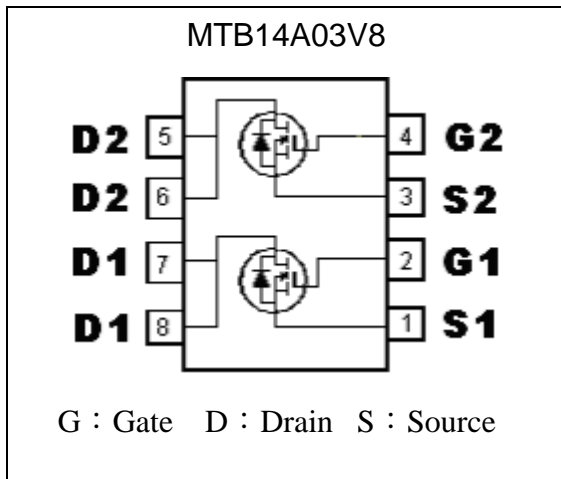
MTB14A03V8

BV_{DSS}	30V	
$I_D @ V_{GS}=10V, T_A=25^\circ C$	8.5A	
$R_{DS(on)(TYP)}$	$V_{GS}=10V, I_D=6A$	11.2m Ω
	$V_{GS}=4.5V, I_D=4A$	16m Ω

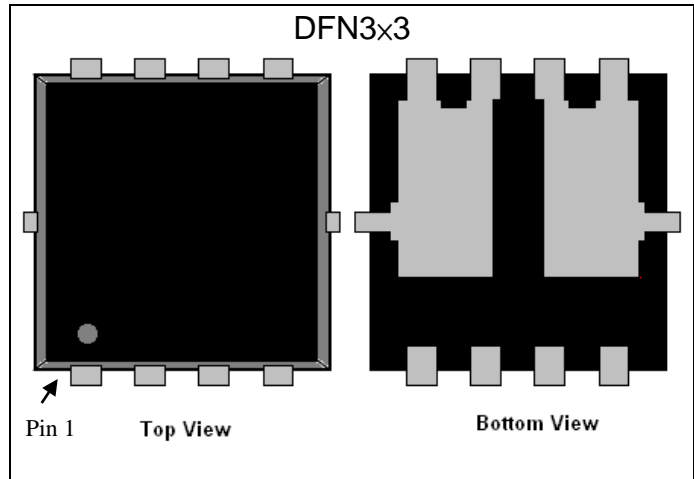
Features

- Single Drive Requirement
- Low On-resistance
- Fast Switching Characteristic
- Dynamic dv/dt rating
- Repetitive Avalanche Rated
- Pb-free lead plating and halogen-free package

Equivalent Circuit

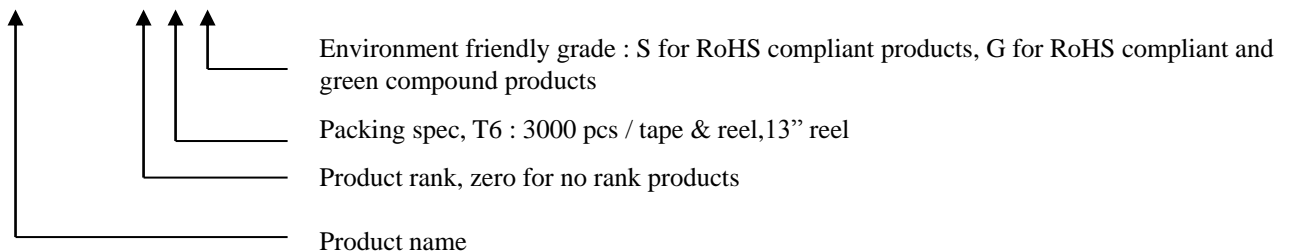


Outline



Ordering Information

Device	Package	Shipping
MTB14A03V8-0-T6-G	DFN3x3 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel





The following characteristics apply to each MOSFET.

Absolute Maximum Ratings (Ta=25°C, unless otherwise specified)

Parameter		Symbol	Limits	Unit
Drain-Source Voltage		V _{DS}	30	V
Gate-Source Voltage		V _{GS}	±20	
Continuous Drain Current @ V _{GS} =10V, T _A =25°C		I _D	8.5	A
Continuous Drain Current @ V _{GS} =10V, T _A =70°C			6.8	
Pulsed Drain Current		I _{DM}	40 *1	
Total Power Dissipation	Single device operation	P _D	1.5 *2	W
	Single device value at dual operation		1.24 *2	
Operating Junction and Storage Temperature Range		T _j , T _{stg}	-55~+150	°C

Thermal Data

Parameter	Symbol	Value	Unit
Max. Thermal Resistance, Junction-to-ambient, single device operation	R _{th,j-a}	84 *2	°C/W
Max. Thermal Resistance, Junction-to-ambient, single device value at dual operation		101 *2	

Note : 1. Pulse width limited by maximum junction temperature.

2. Surface mounted on a 1 in² pad of 2oz copper, t_s≤5s. In practice R_{th,j-a} will be determined by customer's PCB characteristics. 216°C/W when mounted on a minimum pad of 2 oz. copper.

Characteristics (Tc=25°C, unless otherwise specified)

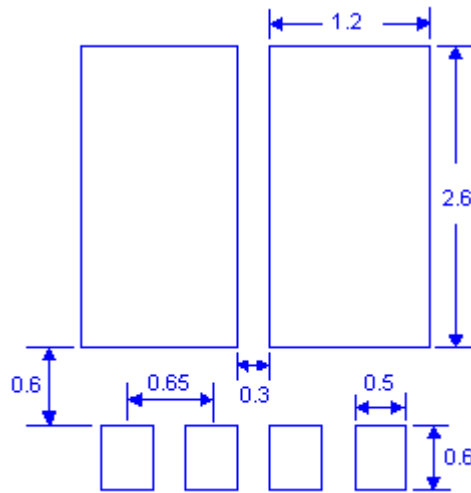
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	30	-	-	V	V _{GS} =0V, I _D =250μA
V _{GS(th)}	1	1.7	2.5		V _{DS} = V _{GS} , I _D =250μA
G _{FS} *1	-	9	-	S	V _{DS} =5V, I _D =6A
I _{GSS}	-	-	±100	nA	V _{GS} =±20V
I _{DSS}	-	-	1	μA	V _{DS} =24V, V _{GS} =0
	-	-	25		V _{DS} =24V, V _{GS} =0, T _j =125°C
R _{DS(ON)} *1	-	11.2	15	mΩ	V _{GS} =10V, I _D =6A
	-	16	23		V _{GS} =4.5V, I _D =4A
Dynamic					
C _{iss}	-	1105	-	pF	V _{DS} =15V, V _{GS} =0V, f=1MHz
C _{oss}	-	117	-		
C _{rss}	-	100	-		
Q _g *1, 2	-	16	-	nC	V _{DS} =15V, V _{GS} =10V, I _D =8.5A
Q _{gs} *1, 2	-	3.3	-		
Q _{gd} *1, 2	-	4	-		
t _{d(ON)} *1, 2	-	12	-	ns	V _{DS} =15V, I _D =1A, V _{GS} =10V, R _{GS} =6Ω
t _r *1, 2	-	9	-		
t _{d(OFF)} *1, 2	-	33	-		
t _f *1, 2	-	12	-		

Characteristics (Tc=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Source-Drain Diode					
I _S *1	-	-	2.3	A	
I _{SM} *3	-	-	9.2		
V _{SD} *1	-	0.74	1.2	V	I _S =2.3A, V _{GS} =0V
trr	-	55	-	ns	I _F =2.3A, dI _F /dt=100A/μs
Qrr	-	6	-	nC	

Note : *1.Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%
 *2.Independent of operating temperature
 *3.Pulse width limited by maximum junction temperature.

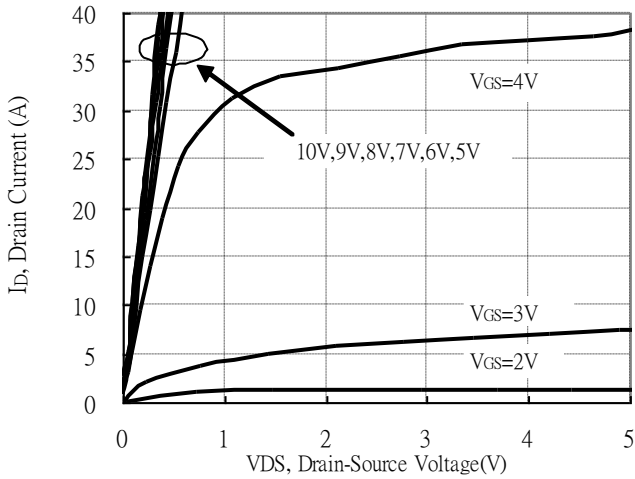
Recommended Soldering Footprint



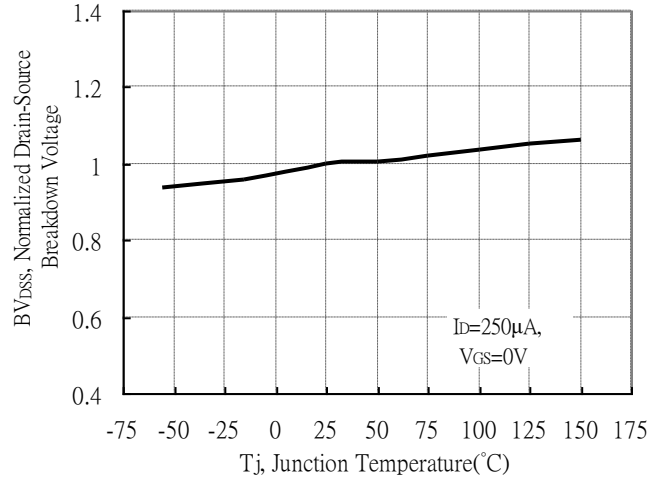
unit : mm

Typical Characteristics

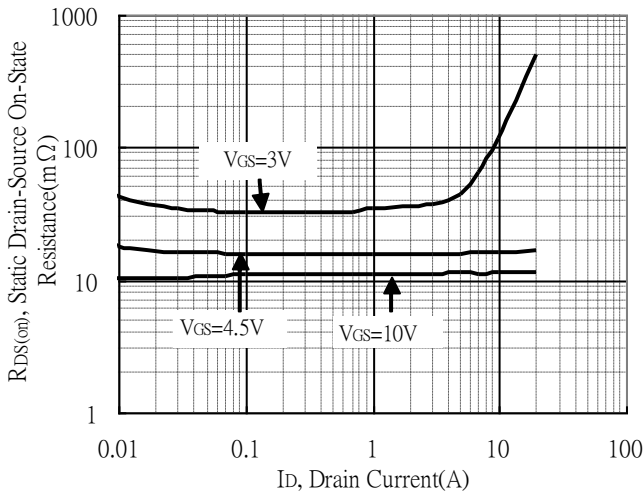
Typical Output Characteristics



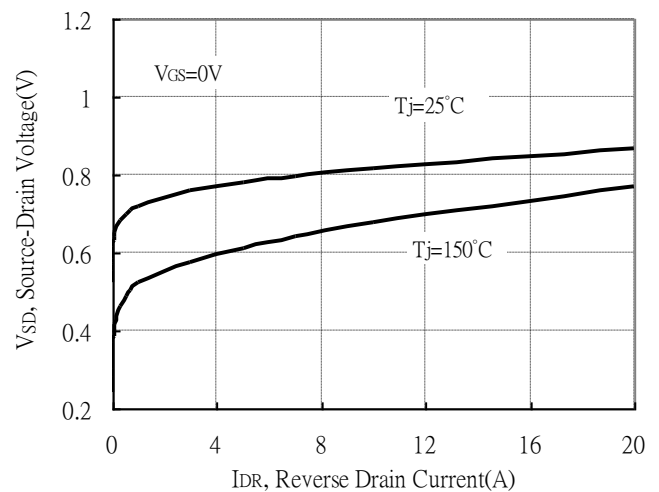
Brekdown Voltage vs Junction Temperature



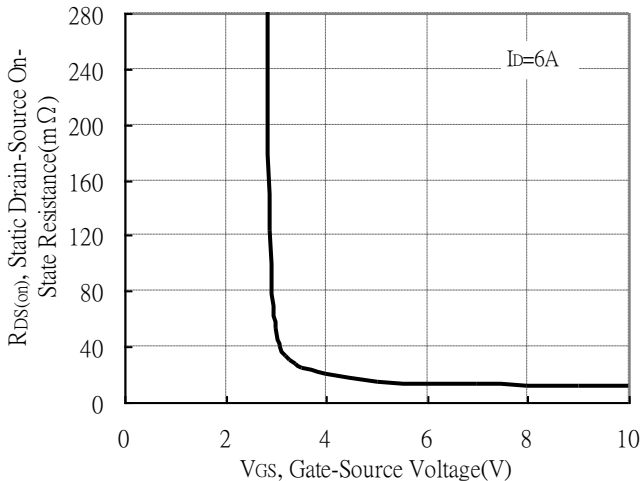
Static Drain-Source On-State resistance vs Drain Current



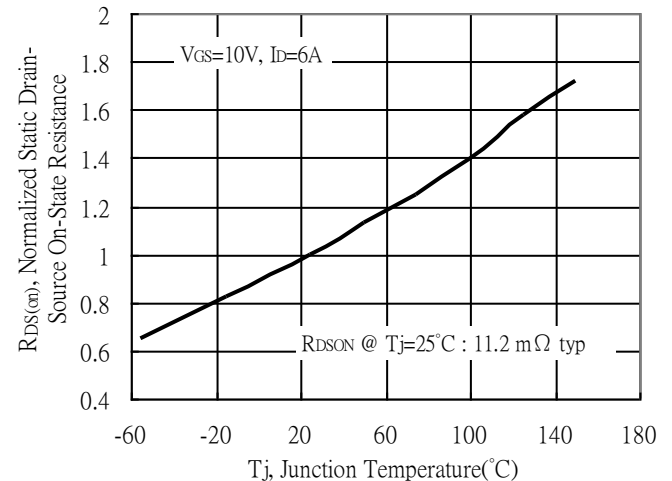
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

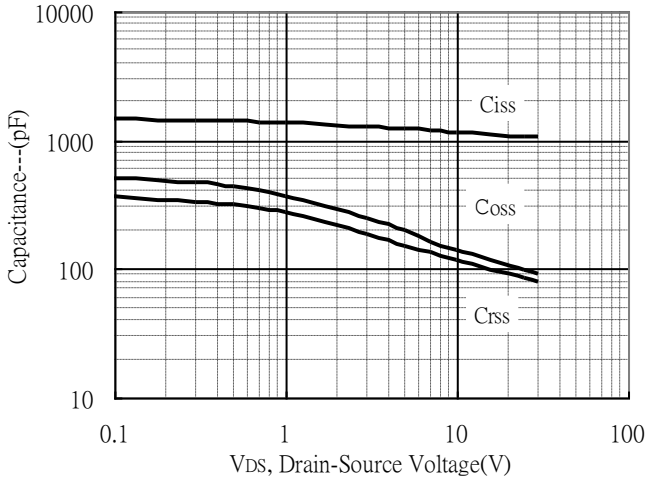


Drain-Source On-State Resistance vs Junction Temperature

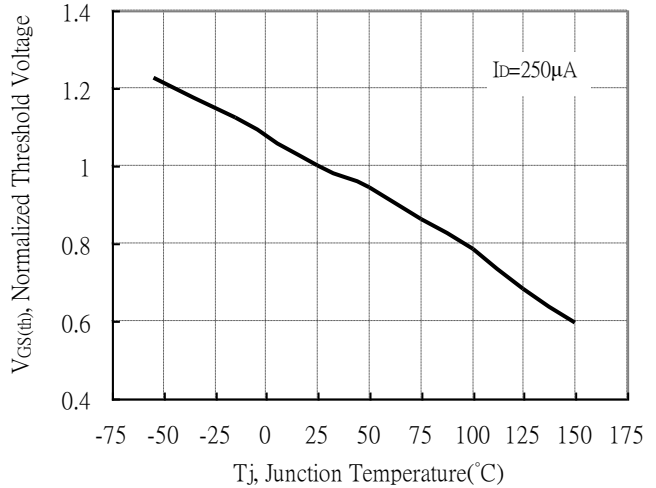


Typical Characteristics(Cont.)

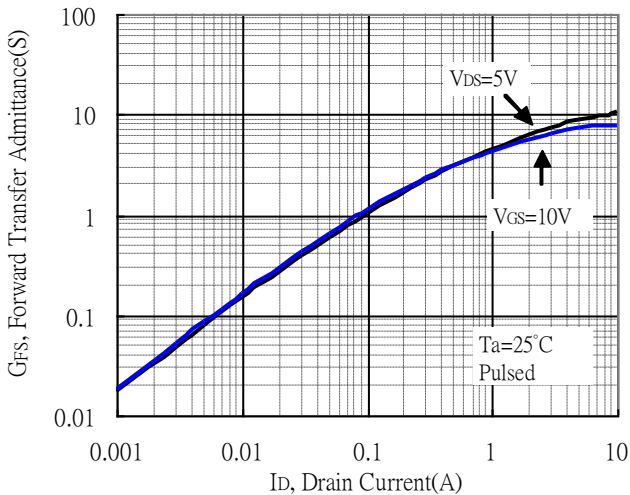
Capacitance vs Drain-to-Source Voltage



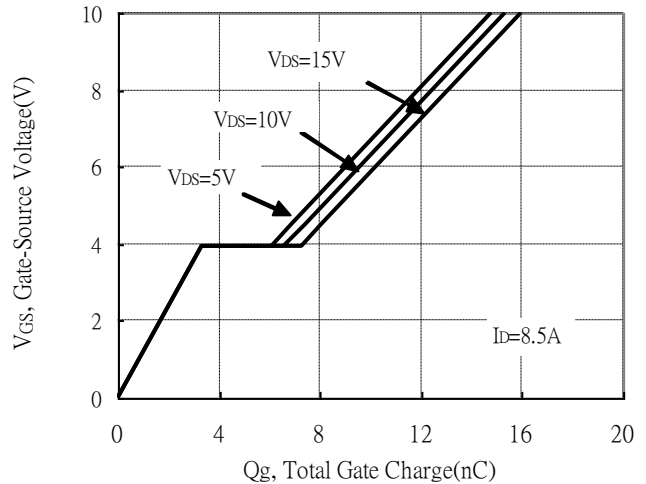
Threshold Voltage vs Junction Temperature



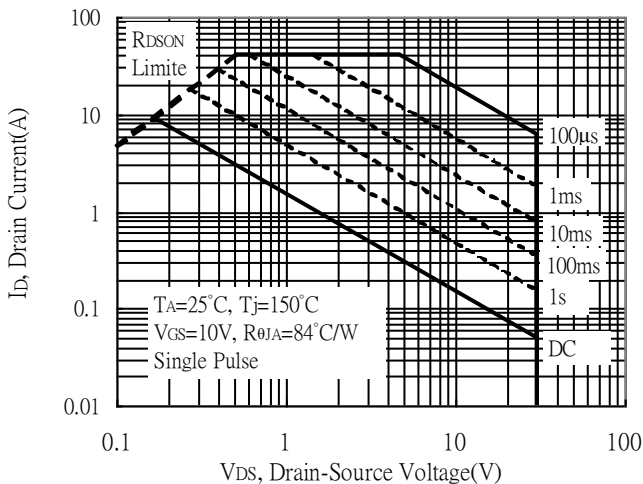
Forward Transfer Admittance vs Drain Current



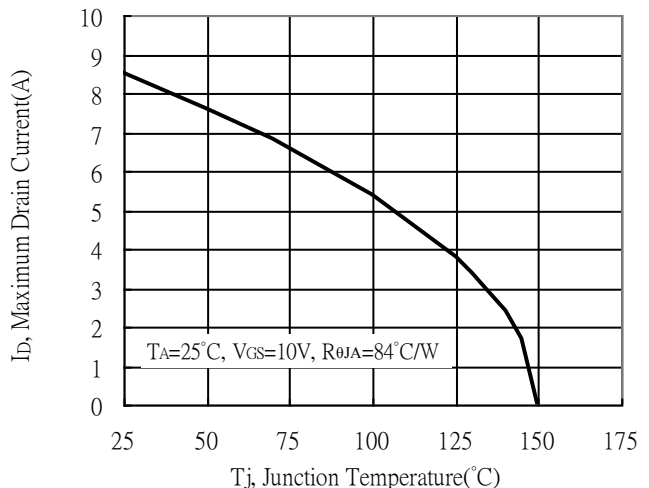
Gate Charge Characteristics



Maximum Safe Operating Area



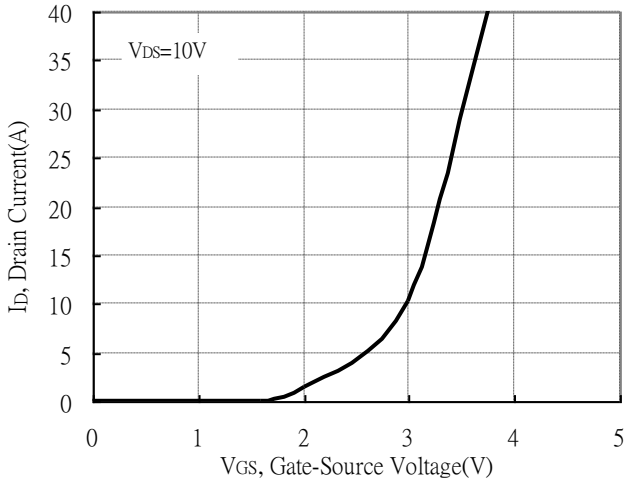
Maximum Drain Current vs Junction Temperature



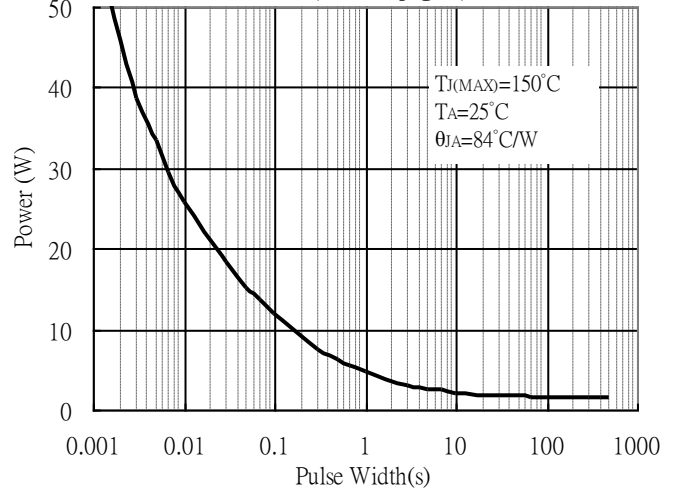


Typical Characteristics(Cont.)

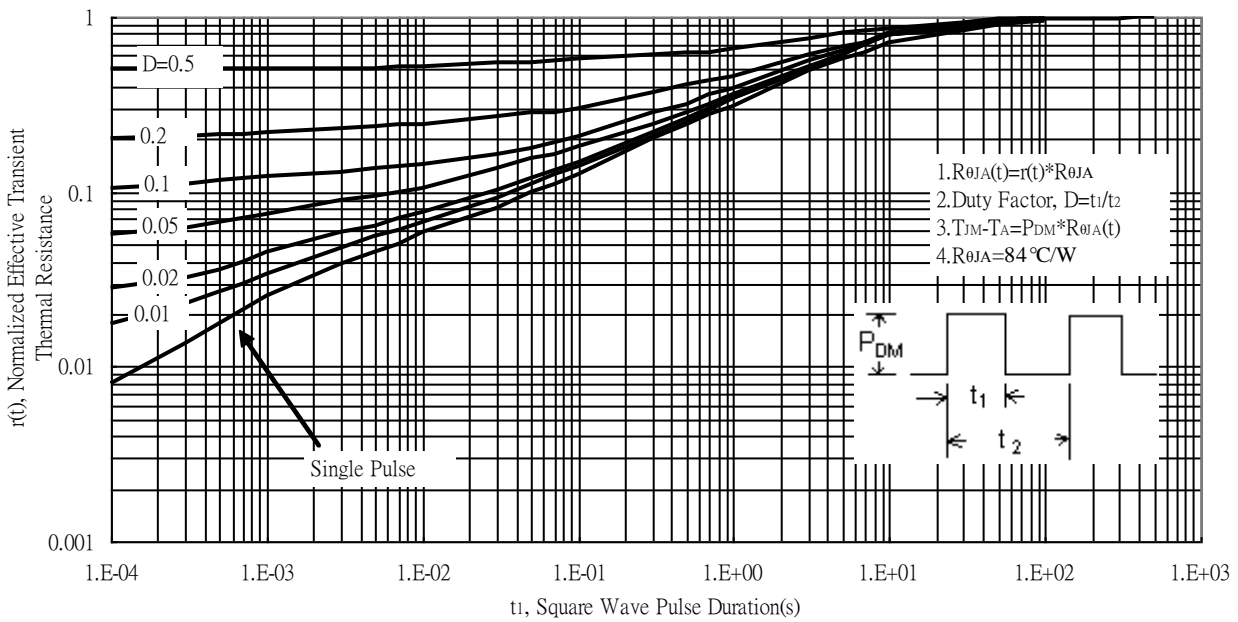
Typical Transfer Characteristics



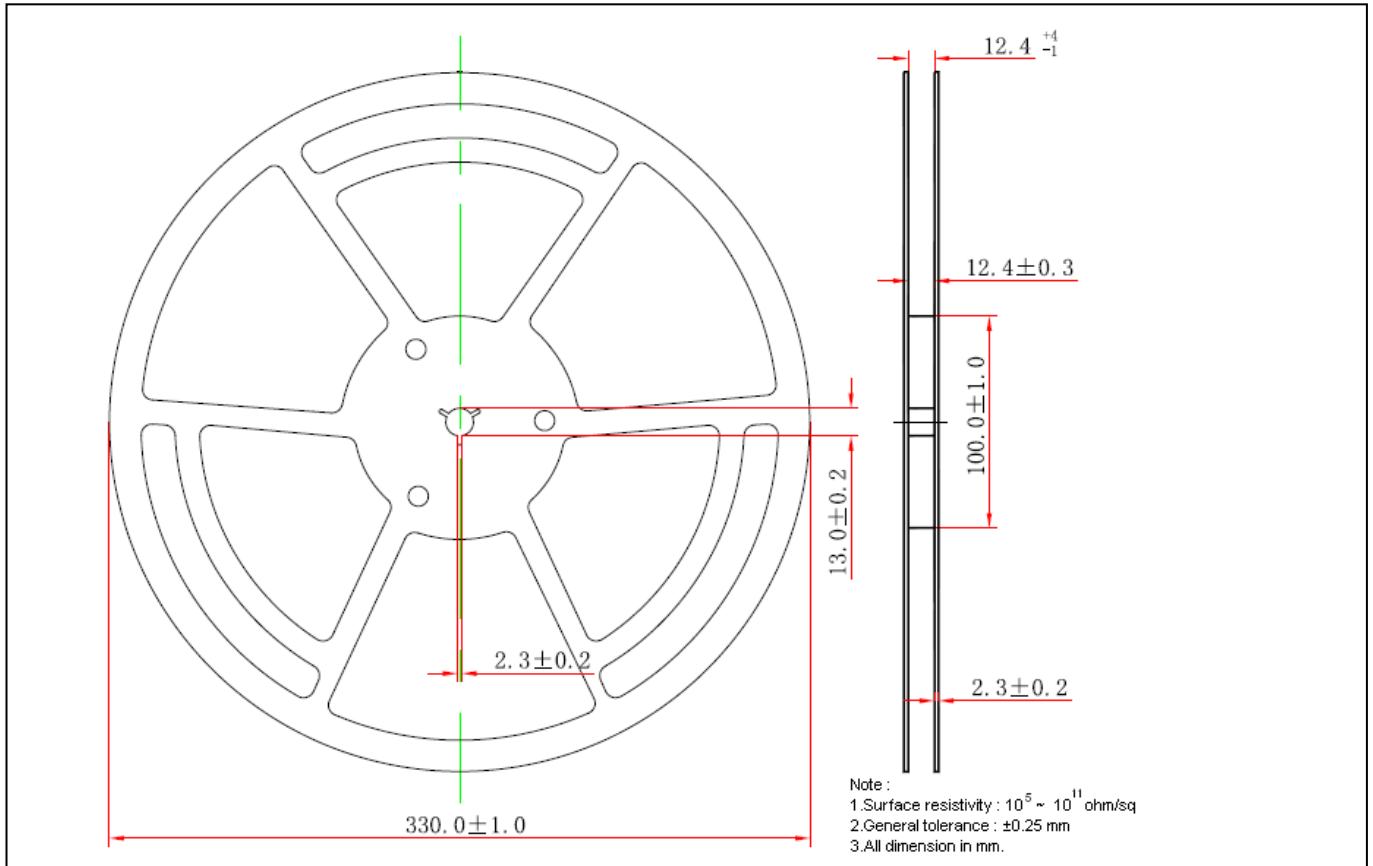
Single Pulse Power Rating, Junction to Ambient
(Note on page 2)



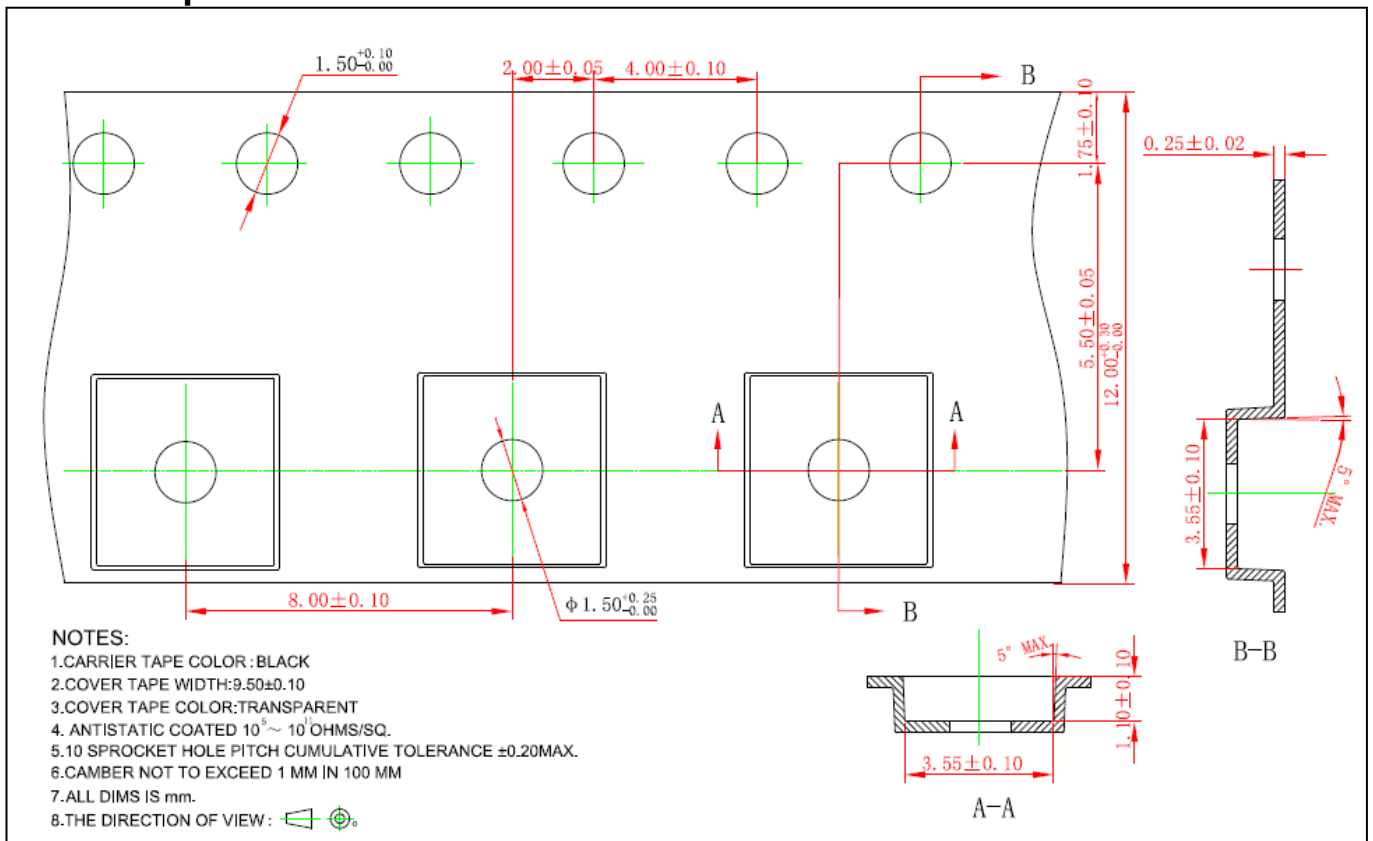
Transient Thermal Response Curves



Reel Dimension



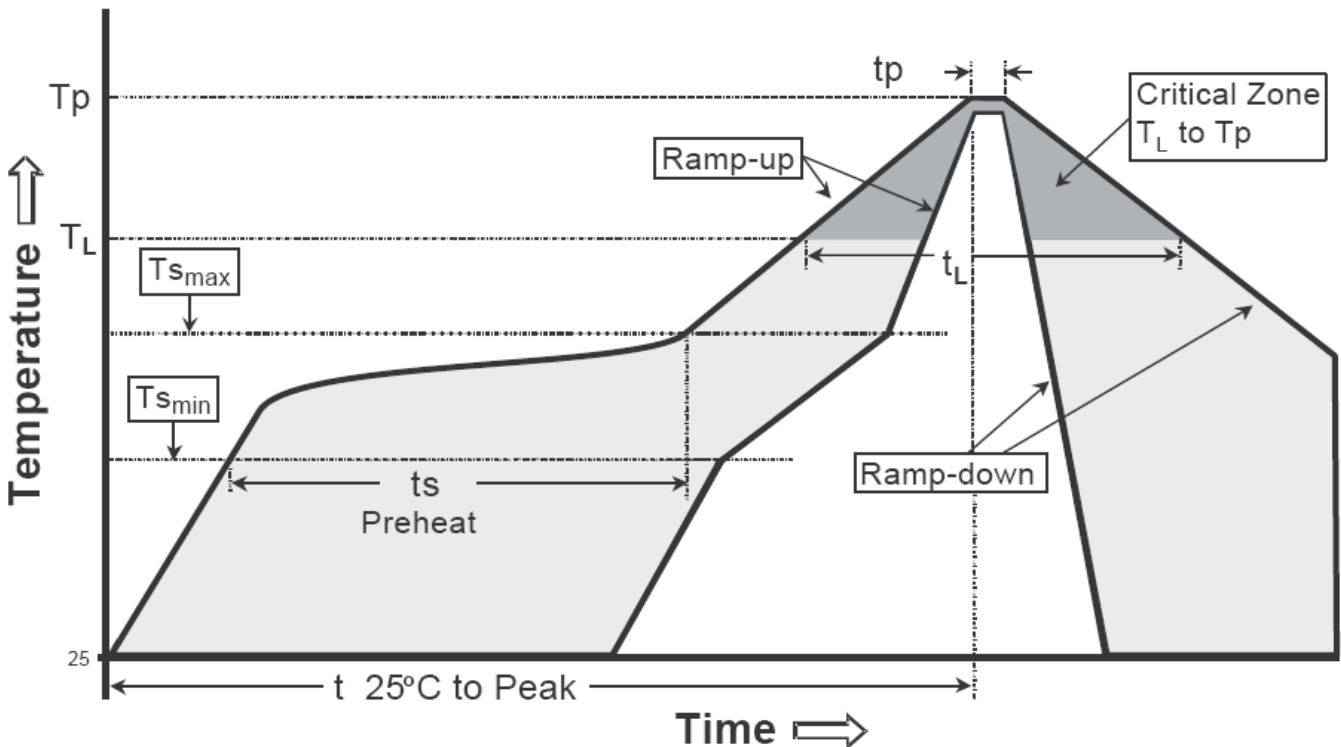
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (TL)	183°C	217°C
- Time (tL)	60-150 seconds	60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

DFN3x3 Dimension

Marking:

Device Code → **B14**
 Date Code → **A03**
 Assembly site code: blank→JCET, G→GEM

S1 G1 S2 G2

Date Code(counting from left to right) :
 1st code: year code, the last digit of Christian year
 2nd code : month code, Jan→A, Feb→B, Mar→C, Apr→D, May→E, Jun→F, Jul→G, Aug→H, Sep→J, Oct→K, Nov→L, Dec→M
 3rd and 4th codes : production serial number, 01~99

8-Lead DFN3x3 Plastic Package
 CYStek Package Code: V8

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033	b	0.200	0.400	0.008	0.016
A1	0.152	REF	0.006	REF	e	0.550	0.750	0.022	0.030
A2	0.000	0.050	0.000	0.002	L	0.300	0.500	0.012	0.020
D	2.900	3.200	0.114	0.126	L1	0.180	0.480	0.007	0.019
D1	0.935	1.135	0.037	0.045	L2	0.130 TYP		0.005 TYP	
D2	0.280	0.480	0.011	0.019	L3	0.130 TYP		0.005 TYP	
E	2.900	3.200	0.114	0.126	H	0.300	0.515	0.012	0.020
E1	3.150	3.450	0.124	0.136	θ	9°	13°	9°	13°
E2	1.535	1.980	0.060	0.078					

- Notes:** 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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